

8 7 6 5 4 3 2 1

NOTES:

1. THE FOLLOWING ABIDES BY THE DSC INSPECTION DOCUMENTATION: # 27-00200-000 .
2. PART MUST WITHSTAND, WITH NO BLISTERING, DELAMINATION, SOLDERMASK FLAKING OR ANY OTHER DAMAGE 3 REFLOW PASSES WITH MAXIMUM TEMPERATURE OF 260± 5° C AND 45 TO 90 SECONDS ABOVE 200° C FOLLOWED BY AQUEOUS OR SONICATED CLEANING.

3. A) MINIMUM DESIGNED CONDUCTOR WIDTH IS 0.005.

B) MINIMUM DESIGNED CONDUCTOR SPACE IS 0.005.

C) MAXIMUM ALLOWABLE LINE REDUCTION DUE TO PIN HOLES, NICKS ON LINE RUNS, AND LINE SHRINKAGE TO BE 10%.

4. MINIMUM LAYER TO LAYER DIELECTRIC FINISH .003, FOR MULTILAYER BOARDS ONLY.
5. COPPER WALL THICKNESS TO MEET IPC-600 CLASS 2.
6. MINIMUM ANNULAR RING PER IPC-6012A (CURRENT REVISION) CLASS 2.
7. ALL PHYSICAL ALIGNMENT MARKS ARE TO BE PLATED PER THE PROCESS BELOW. MAXIMUM 10% SIZE REDUCTION ALLOWED. 250 SOLDERMASK CLEARANCE AROUND PDUOALS.
8. SOLDERMASK : MASK HEIGHT MUST NOT EXCEED .0014 INCHES.
9. SOLDERMASK REGISTRATION TO BE ± .003.
10. SIDE TO SIDE REGISTRATION TO BE ± .003.
11. REMOVE ALL BURRS AND SHARP EDGES IN ORDER TO MEET DIMENSIONAL TOLERANCES.
12. THE FOLLOWING MUST BE PRESENT & LOCATED PER PAGE 2. (ETCHED, SOLDERMASK, SILKSCREENED OR STAMPED WITH NON-CONDUCTIVE INK).
  - A) "PART NUMBER"
  - B) "REVISION LETTER"
  - C) "SIDE A" FOR SIDE A, "SIDE B" FOR SIDE B.
  - D) DATE CODE
  - E) MANUFACTURER'S UL LOGO
13. EXTERNAL COPPER WEIGHT WILL NOT EXCEED 1.5 OZ.
14. MAXIMUM ALLOWABLE WARP PER IPC-600.
15. SOLDERMASK ARTWORK MUST NOT BE EDITED IN ANY WAY. THE ARTWORK MANDATES A MINIMUM CLEARANCE AROUND BOARD EDGE TO REDUCE PEEING AND KEEP MASK OFF EDGE CONNECTORS AND LEAD FRAME PADS IF APPLICABLE.

- PROCESSES: SOLDERMASK OVER BARE COPPER (SMOBC) AND ELECTROLESS NI IMMERSION GOLD (ENIG). MUST MEET IPC-S-804 SOLDERABILITY.
- 1.) Au (IMMERSION 3-10 MICRO INCHES).
  - 2.) Ni (ELECTROLESS 100-300 MICRO INCHES).
  - 3.) SOLDERMASK PER IPC-SM-840 (CURRENT REVISION), USING ARTWORK NO. 1 FOR SIDE A AND NO. 4 FOR SIDE B.

- PROCESSES: ELECTROLYTIC Ni GOLD MUST MEET IPC-S-804 SOLDERABILITY.
- 1.) Au (ELECTROLYTIC 10-30 MICRO INCHES).
  - 2.) Ni (ELECTROLYTIC 100-500 MICRO INCHES).
  - 3.) SOLDERMASK PER IPC-SM-840 (CURRENT REVISION), USING ARTWORK NO. 1 FOR SIDE A AND NO. 4 FOR SIDE B.

TABLE FOR ARTWORK

NO.	DESCRIPTION	STARTING COPPER WT.	REVISION
1	SIDE A SOLDER MASK		A
2	LAYER 1 SURFACE (SIDE A)	0.5 OZ.	A
3	LAYER 2 SURFACE (SIDE B)	0.5 OZ.	A
4	SIDE B SOLDER MASK		A

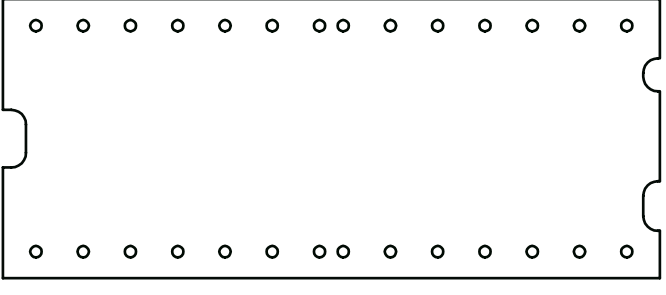
DRILL/TEST DATA

DESCRIPTION	SIDE	REVISION
HOLE CONFIGURATION	A	A
HOLE CONFIGURATION	B	
CONTINUITY TEST	A	
CONTINUITY TEST	B	
PROFILE	A	
PROFILE	B	

SELECTION

1	2	3	4
SE	NI	PC	SM
15	8	9	15

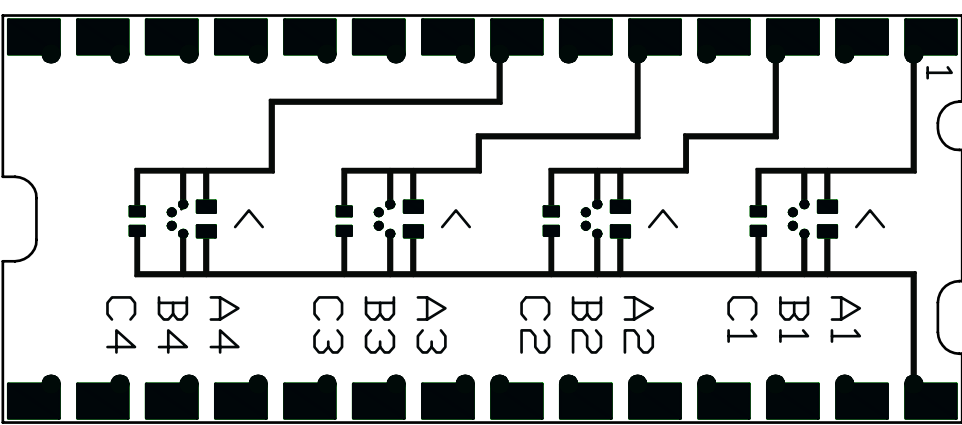
- PROCESSES: ELECTROLYTIC Ni GOLD MUST MEET IPC-S-804 SOLDERABILITY.
- 1.) Au (ELECTROLYTIC 10-30 MICRO INCHES).
  - 2.) Ni (ELECTROLYTIC 100-500 MICRO INCHES).
  - 3.) SOLDERMASK PER IPC-SM-840 (CURRENT REVISION), USING ARTWORK NO. 1 FOR SIDE A AND NO. 4 FOR SIDE B.



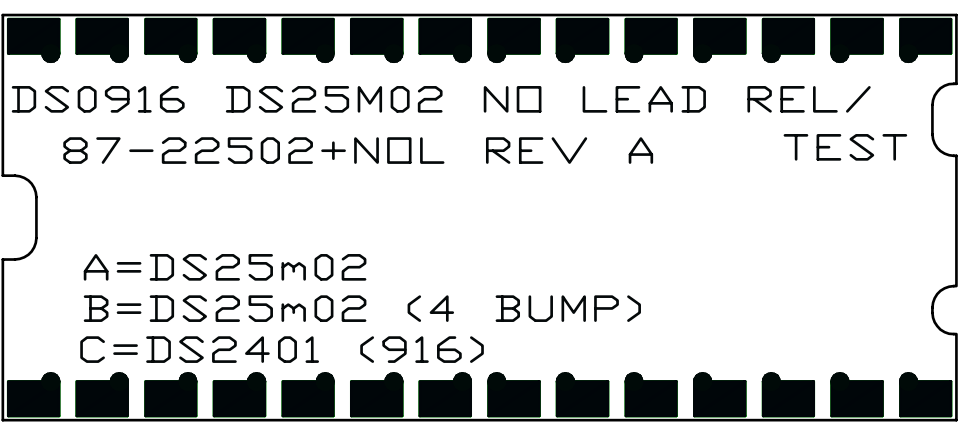
☒ = CRITICAL DIMENSION  
HOLE SCHEDULE

SYM	FINISHED HOLE DIAMETER	UNSUPPORTED PLATED THRU +.007-.003	HOLE COUNT	REMARKS
☒	.120 ±.003	--	0	CELL PANEL
○	.012		28	4 PANEL TOOLING HOLES

SIDE - A



SIDE - B

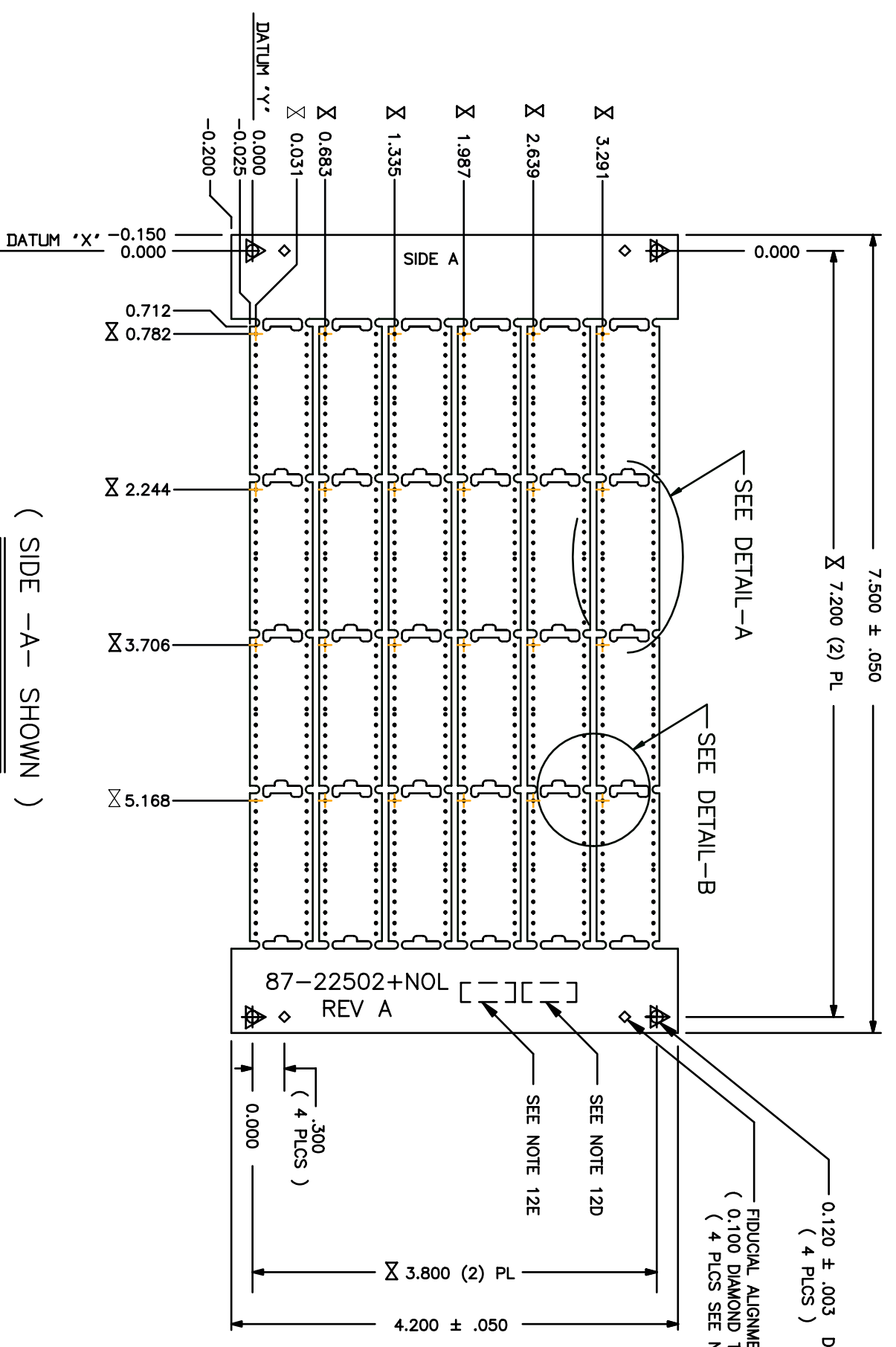


DRILLS (REFERENCE ONLY NOT TO SCALE)  
( SIDE A SHOWN )

8 7 6 5 4 3 2 1

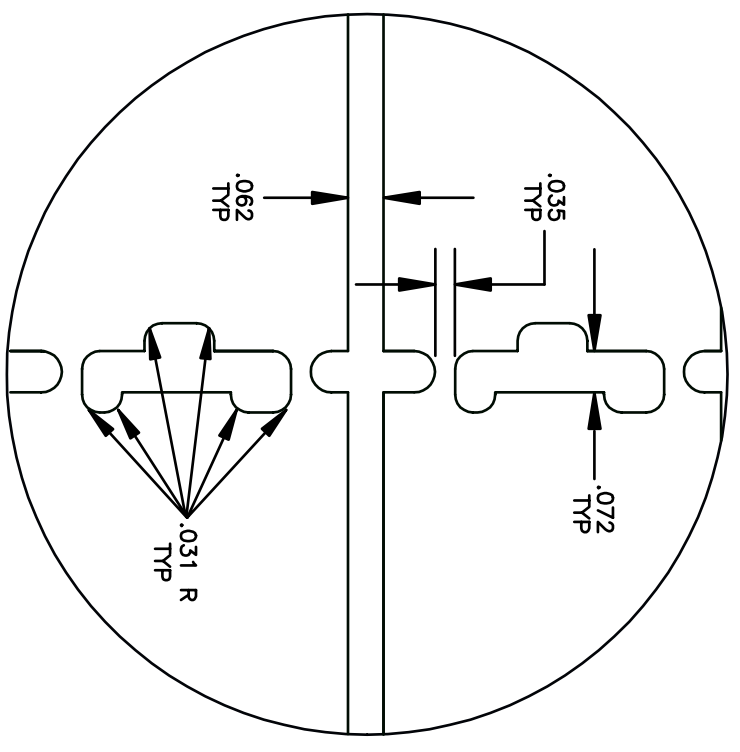
.041  $\pm$ .002  $\times$  ( TOTAL OVERALL THICKNESS )  
( OVER PLATING )

( SIDE VIEW )



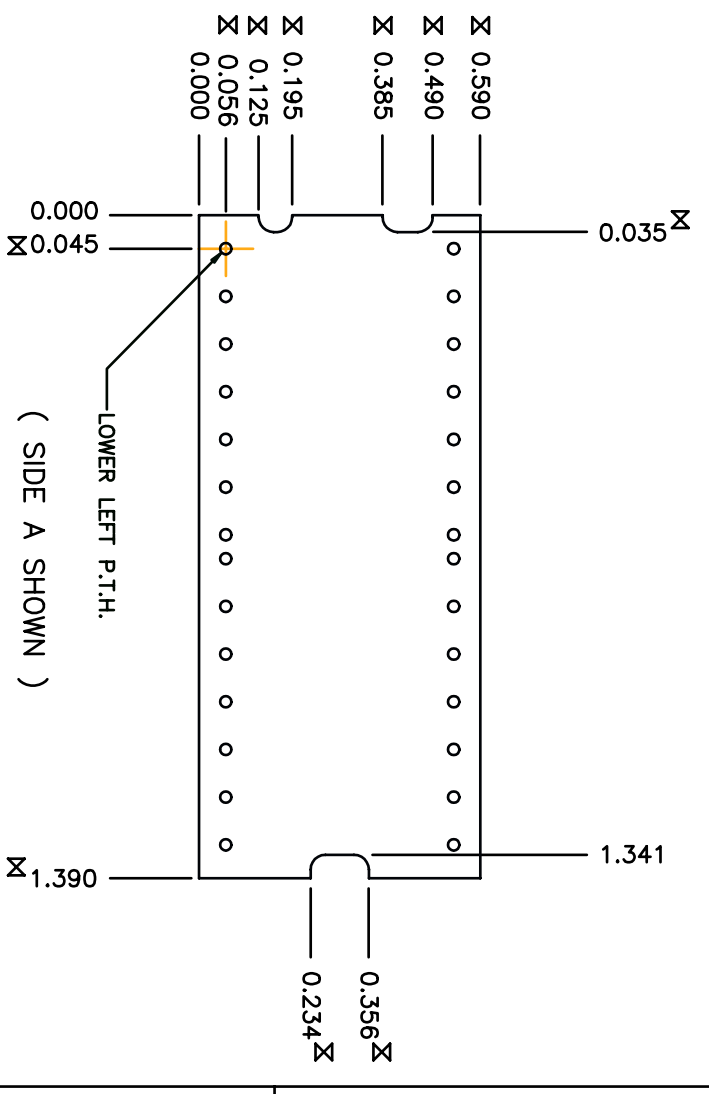
( SIDE -A- SHOWN )

SCALE = 1.5 : 1



DETAIL-B

SCALE = 6:1



( SIDE A SHOWN )

DETAIL-A

SCALE = 5:1

DALLAS MAXIM

